SMTA INTERMOUNTAIN CHAPTER VENDOR DAYS AND FREE TECHNICAL CONFERENCE

Co-sponsor: Boise State University

Tuesday, March 22
Boise State University
Student Union Building
Simplot Ballroom
Boise, Idaho

Attendees: ATTENDEE REGISTRATION IS FREE. See attached registration form to sign up. **Lunch for attendees is also FREE with registration.** Register now to visit with representatives from major suppliers to the industry. Join us for free networking, free technical sessions and free lunch. **FREE lunch will not be available for those who register after March 19.** Registration at the

The cost to exhibit is $300 on or before March 1, and $350 after March 1. SMTA members save an additional 10% on the cost to exhibit. The price includes table, two chairs, attendee list, basic electrical outlet and lunch.

Exhibitors: Please see attached registration form and proposed layout. Register early to reserve the space you want. Exhibitor space is limited. Coffee break, Lunch and door prize sponsors are welcome.

Conference Agenda:

9:00 AM Registration, Social Networking, Vendor Tables
9::45 AM **Speaker: Mr. Jim Luginbill** VP Strategic Development, Jabil Circuits
"EMS Industry Growth; Strategic vs Tactical"
11:00AM **Speaker: Dr. Andy C. Mackie** Global Product ManagerSemiconductor and Advanced Assembly Materials, Indium Corp
12:00 PM Lunch, Visit Vendor Tables
1:30 PM **Speaker: Michael Kochanowski** Intel Corp Adhesive Methods to Re-enforce Electronics Packages at the board lever for Reliability.
2:45 PM **Speaker Paul Wood** OK International: Reworking PoP (Package on Package Components)
3:45 PM Door Prize Drawing Over $150.00 in Prizes

Questions: Contact David Bell david.bell@plexus.com 208-867- 6006

Jim Luginbill has been a Vice President and Officer for Jabil since March 2005. He joined Jabil in 1998 as a Business Unit Director responsible for the Hewlett Packard account and was promoted to Senior Business Unit Director in 2002. In 2005, Mr. Luginbill was made Vice President, Global Business Units and assumed sector ownership for several global accounts where he successfully managed the growth and globalization of customers in the Enterprise, Storage, Peripherals, and Display industries. In 2009, he became Vice President, Strategic Development focused on Emerging Markets. Prior to Jabil, Mr. Luginbill held various manufacturing positions with Hewlett-Packard including management responsibilities in Engineering and Product Development and Support. Mr. Luginbill holds a B.S. in Chemical Engineering from Oregon State University. He is married and has two grown children.

SMTA Presentation: "EMS Industry Growth; Strategic vs Tactical"

Abstract:
The trend for outsourcing continues to expand as the complexities of the world market drive product companies to be more competitive and more focused on their core capabilities. This has opened the door to the EMS indus-

Andy C. Mackie is the Global Product Manager for Indium Corporation's Semiconductor Assembly Materials and the author of the Semiconductor Assembly Blog. Andy has over 20 years of experience in new product and process development and materials marketing in all areas of electronics manufacturing, including: Wafer fabrication,Electronics assembly, Semiconductor packaging. Andy is an electronics industry expert in physical chemistry, surface chemistry, rheology, solder materials properties and processes (including solder paste printing), and reflow. Andy received the prestigious IPC President's Award in 2001 for his leadership in both the Solder Paste Task Group and the Assembly and Joining Materials sub-committee.He is formally trained in Six Sigma's Design of Experiments. Andy has written papers and lectured internationally on subjects ranging from sub-ppb metals analysis in supercritical carbon dioxide to pin-probe testing of flux residues. Additionally, Andy holds patents in novel polymers, gas analysis, and solder paste formulation. Andy has a PhD in Physical Chemistry from the University of Nottingham, UK, and a Masters of Science (MSc) in Surface and Colloid Chemistry from the University of Bristol, UK.

Michael Kochanowski received a BS in chemical engineering (1983) and an MS in industrial administration (1990) both from Carnegie Mellon University in Pittsburgh, Pennsylvania. He is a member of Tau Beta Pi. His career interests include organic and polymer synthesis chemistry, mathematical modeling and process optimization. Mike has spent ten years in process development with the pharmaceutical company, Merck & Co., Inc. and fourteen years in circuit board development with Intel Corporation. He is Intel's technical leader in the use of adhesives for reliability improvement in board level applications.

SMTA presentation: Adhesive Methods to Re-enforce Electronics Packages at the board lever for Reliability

Abstract:
Electronic packages by themselves are often not robust enough to pass reliability demands. This paper gives an in depth analysis of various adhesive approaches to re-enforce electronics packages at the board level to improve reliability.

Paul Wood is an industry expert in the BGA/CSP/Array package rework arena. With 27 years of service at OK International, Inc., and 35 years experience in the electronics assembly industry, Mr. Wood has used his global experience in rework to keep electronic assembly manufacturers on the leading edge of technology.
Mr. Wood is an Advanced Product Applications Manager for OK International, specializing in new technology rework applications. He is also an expert in working with lead-free advanced BGA packaging rework equipment.
Mr. Wood works extensively with component manufacturers and advanced packaging professionals to find the latest rework solutions, and incorporates new processes for them into the design of their rework systems. Mr. Wood is often asked to present papers and seminars on BGA/CSP rework at conferences worldwide.
Born n Liverpool, England, UK, he has resided in the USA for the past 15 years.
Mr. Wood is married and lives in Pleasanton, CA. He is based at OK International's worldwide headquarters in Garden Grove, CA.

SMTA presentation: Reworking PoP (Package on Package Components) New Challenges for the BGA Rework with Double Sided Lead-Free PCBs

Abstract:

This paper provides new and inventive ways to overcome the Rework challenges presented by lead-free and new package on package components. Requirements for strict temperature control are crucial for top to bottom temperatures' across the stacks. Equipment must provide these higher levels of control and innovative methods to remove and replace these components.